

QL16x24B pASIC[®] 1 Family Very-High-Speed CMOS FPGA

Rev C

pASIC HIGHLIGHTS

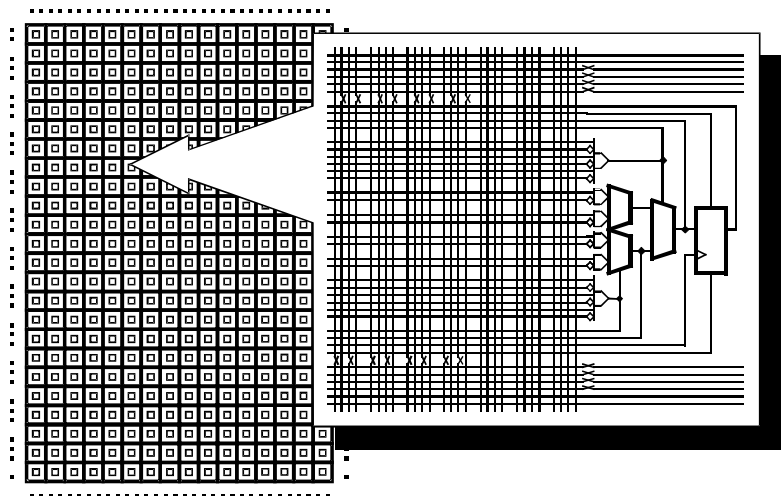
*...4,000
usable ASIC gates,
122 I/O pins*

QL16x24B Block Diagram

384 Logic Cells



- ✘ **Very High Speed** – ViaLink[®] metal-to-metal programmable–via antifuse technology, allows counter speeds over 150 MHz and logic cell delays of under 2 ns.
- ✘ **High Usable Density** – A 16-by-24 array of 384 logic cells provides 4,000 usable ASIC gates (7,000 PLD gates) in 84-pin PLCC, 100-pin and 144-pin TQFP, 144-pin CPGA and 160-pin CQFP packages.
- ✘ **Low-Power, High-Output Drive** – Standby current typically 2 mA. A 16-bit counter operating at 100 MHz consumes less than 50 mA. Minimum IOL of 12 mA and IOH of 8 mA
- ✘ **Low-Cost, Easy-to-Use Design Tools** – Designs entered and simulated using QuickLogic's new QuickWorks[®] development environment, or with third-party CAE tools including Viewlogic, Synopsys, Mentor, Cadence and Veribest. Fast, fully automatic place and route on PC and workstation platforms using QuickLogic software.



▪ = Up to 114 prog. I/O cells, 6 Input high-drive cells, 2 Input/Clk (high-drive) cells

**PRODUCT SUMMARY**

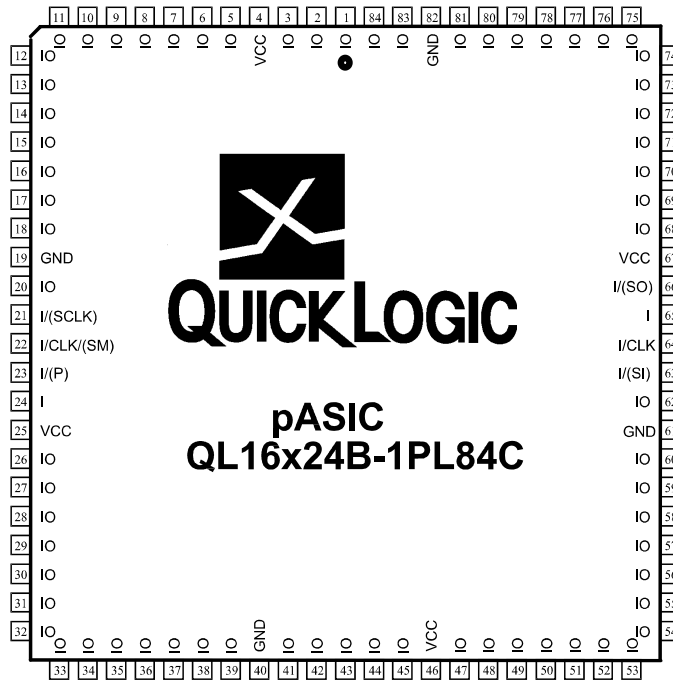
The QL16x24B is a member of the pASIC 1 Family of very-high-speed CMOS user-programmable ASIC devices. The 384 logic cell field-programmable gate array (FPGA) offers 4,000 usable ASIC gates (equivalent to 7,000 PLD gates) of high-performance general-purpose logic in 84-pin PLCC, 100-pin and 144-pin TQFP, 144-pin CPGA, and 160-pin CQFP.

Low-impedance, metal-to-metal, ViaLink interconnect technology provides nonvolatile custom logic capable of operating above 150 MHz. Logic cell delays under 2 ns, combined with input delays of under 1.5 ns and output delays under 3 ns, permit high-density programmable devices to be used with today's fastest microprocessors and DSPs.

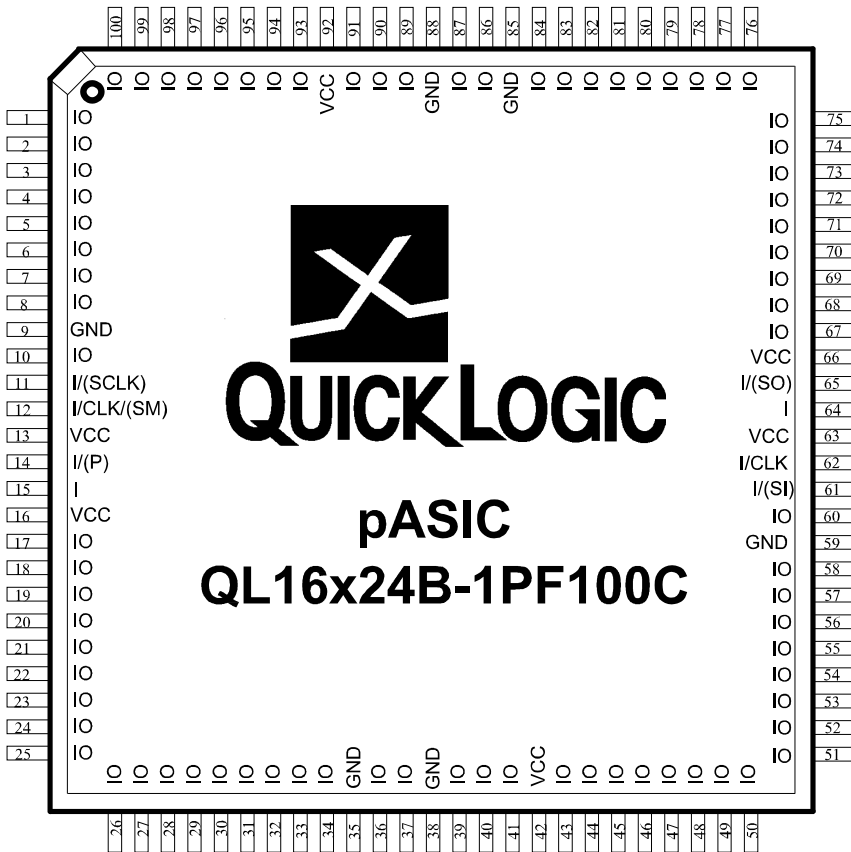
Designs can be entered using QuickLogic's QuickWorks Toolkit or most popular third-party CAE tools. QuickWorks combines Verilog/VHDL design entry and simulation tools with device-specific place & route and programming software. Ample on-chip routing channels allow fast, fully automatic place and route of designs using up to 100% of the logic and I/O cells, while maintaining fixed pin-outs.

FEATURES

- ☒ Total of 122 I/O pins
 - 114 Bidirectional Input/Output pins
 - 6 Dedicated Input/High-Drive pins
 - 2 Clock/Dedicated input pins with fanout-independent, low-skew clock networks
- ☒ Input + logic cell + output delays under 6 ns
- ☒ Chip-to-chip operating frequencies up to 110 MHz
- ☒ Internal state machine frequencies up to 150 MHz
- ☒ Clock skew < 0.5 ns
- ☒ Input hysteresis provides high noise immunity
- ☒ Built-in scan path permits 100% factory testing of logic and I/O cells and functional testing with Automatic Test Vector Generation (ATVG) software after programming
- ☒ Packages are 84-pin PLCC, 100-pin and 144-pin TQFP, 144-pin CPGA, and 160-pin CQFP
- ☒ 84-pin PLCC compatible with QL12x16B
- ☒ 100-pin TQFP compatible with QL8x12B and QL12x16B
- ☒ 144-pin TQFP compatible with QL24x32B
- ☒ 0.65µ CMOS process with ViaLink programming technology



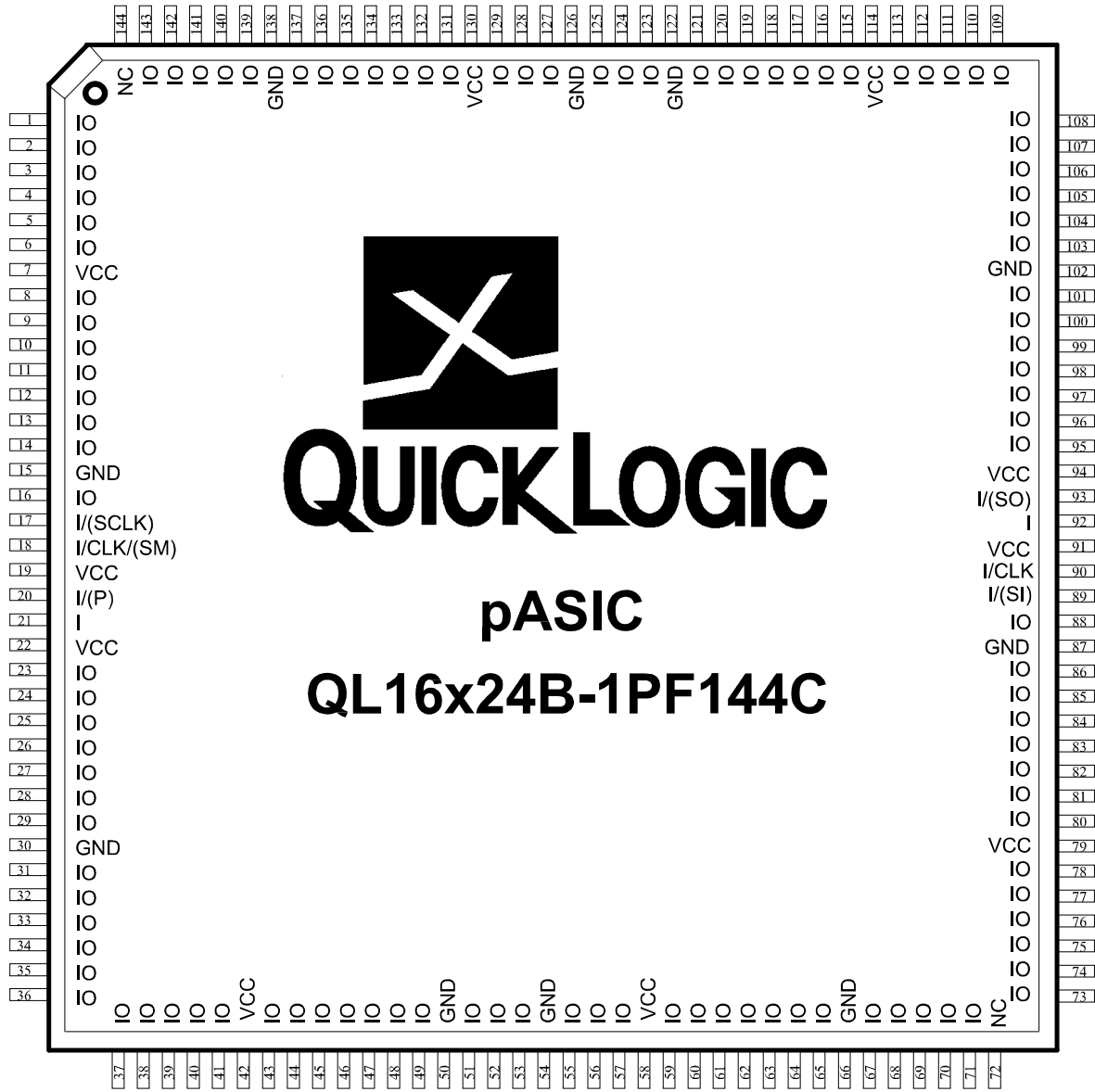
Pinout Diagram
84-pin PLCC



Pinout Diagram
100-pin TQFP

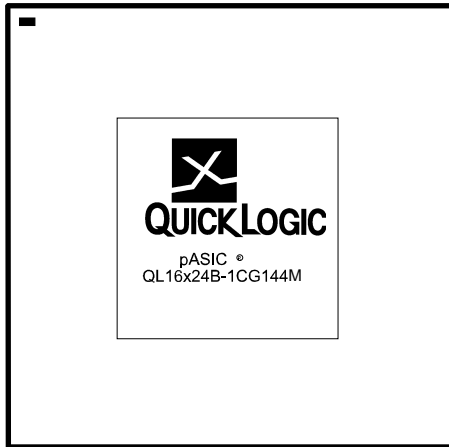


Pinout Diagram
144-pin TQFP

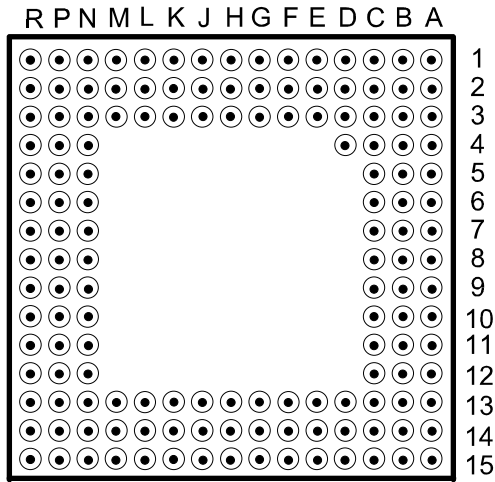




TOP VIEW



BOTTOM VIEW



Pinout Diagram
144-pin CPGA

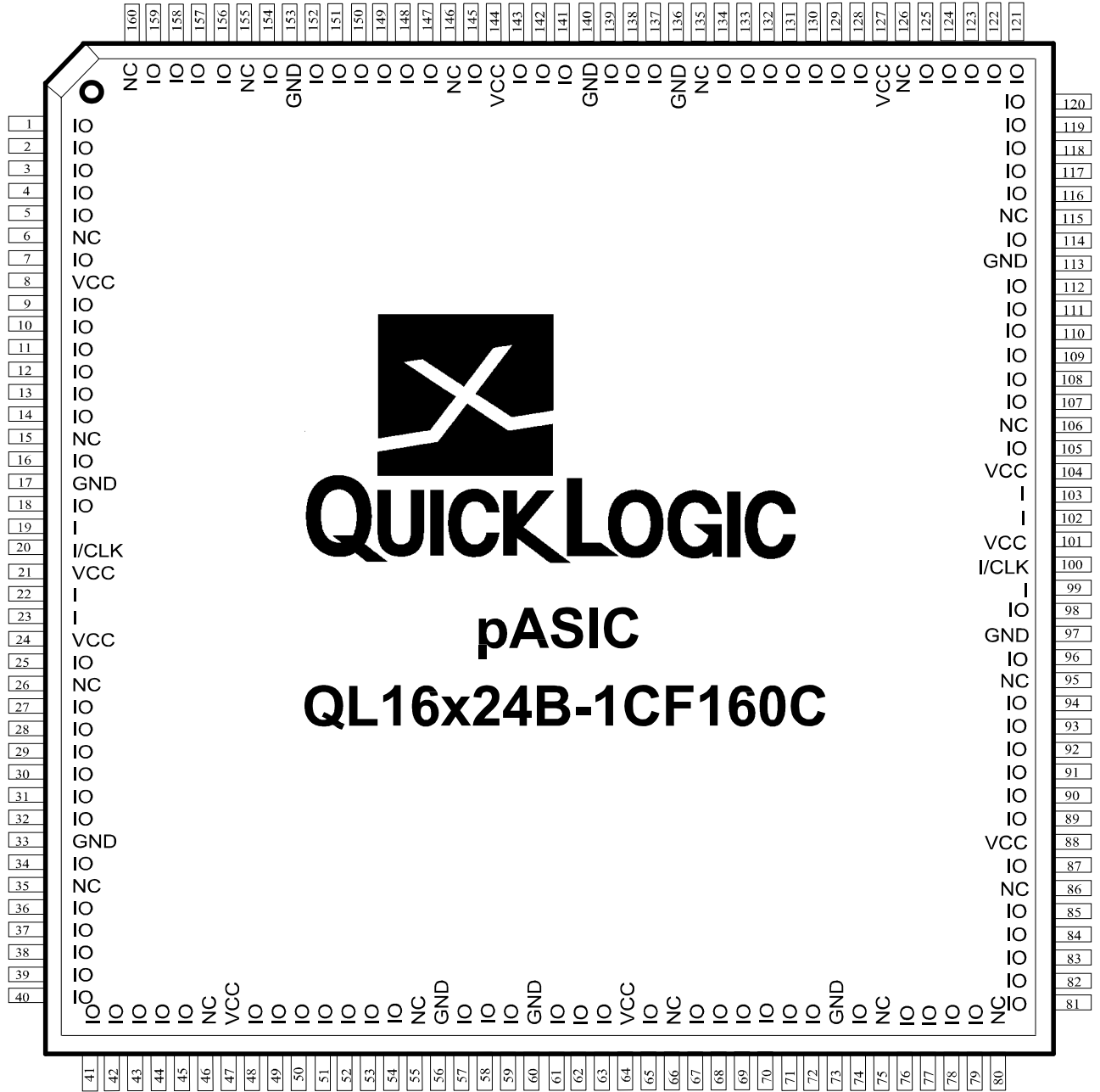


CPGA 144 Function/Connector Table

| PIN | FUNC | PIN | FUNC | PIN | FUNC | PIN | FUNC |
|-----|------------|-----|------|-----|--------|-----|------|
| A2 | IO | B15 | IO | R14 | IO | P1 | IO |
| B3 | IO | C14 | IO | P13 | IO | N2 | IO |
| C4 | IO | D13 | IO | N12 | IO | M3 | IO |
| A3 | IO | C15 | IO | R13 | IO | N1 | IO |
| B4 | IO | D14 | IO | P12 | IO | M2 | IO |
| A4 | IO | E13 | VCC | R12 | IO | L3 | VCC |
| C3 | VCC | D15 | IO | N13 | VCC | M1 | IO |
| B5 | IO | E14 | IO | P11 | IO | L2 | IO |
| A5 | IO | E15 | IO | R11 | IO | L1 | IO |
| C6 | IO | F13 | IO | N10 | IO | K3 | IO |
| B6 | IO | F14 | IO | P10 | IO | K2 | IO |
| A6 | IO | F15 | IO | R10 | IO | K1 | IO |
| A7 | IO | G15 | IO | R9 | IO | J1 | IO |
| B7 | IO | C13 | GND | P9 | IO | N3 | GND |
| C5 | GND | G14 | IO | N11 | GND | J2 | IO |
| A8 | IO | H15 | IO | R8 | IO | H1 | IO |
| B8 | I/(SCLK) | H14 | IO | P8 | I/(SI) | H2 | IO |
| C8 | I/CLK/(SM) | G13 | GND | N8 | I/CLK | J3 | GND |
| C7 | VCC | H13 | IO | N9 | VCC | H3 | IO |
| A9 | I/(P) | J15 | IO | R7 | I | G1 | IO |
| B9 | I | J14 | IO | P7 | I/(SO) | G2 | IO |
| C11 | VCC | J13 | VCC | N5 | VCC | G3 | VCC |
| A10 | IO | K15 | IO | R6 | IO | F1 | IO |
| A11 | IO | L15 | IO | R5 | IO | E1 | IO |
| B10 | IO | K14 | IO | P6 | IO | F2 | IO |
| A12 | IO | M15 | IO | R4 | IO | D1 | IO |
| B11 | IO | L14 | IO | P5 | IO | E2 | IO |
| C10 | IO | K13 | IO | N6 | IO | F3 | IO |
| A13 | IO | N15 | IO | R3 | IO | C1 | IO |
| C9 | GND | L13 | GND | N7 | GND | E3 | GND |
| B12 | IO | M14 | IO | P4 | IO | D2 | IO |
| A14 | IO | P15 | IO | R2 | IO | B1 | IO |
| B13 | IO | N14 | IO | P3 | IO | C2 | IO |
| C12 | IO | M13 | IO | N4 | IO | D3 | IO |
| A15 | IO | R15 | IO | R1 | IO | A1 | IO |
| B14 | IO | P14 | nc | P2 | IO | B2 | nc |



Pinout Diagram
160-pin CQFP



4
pASIC 1

**ABSOLUTE MAXIMUM RATINGS**

Supply Voltage -0.5 to 7.0V
 Input Voltage -0.5 to VCC +0.5V
 ESD Pad Protection ±2000V
 DC Input Current ±20 mA
 Latch-up Immunity ±200 mA

Storage Temperature -65°C to + 150°C
 Lead Temperature 300°C

OPERATING RANGE

| Symbol | Parameter | Military | | Industrial | | Commercial | | Unit | |
|--------|---------------------|----------------|-----|------------|------|------------|------|------|------|
| | | Min | Max | Min | Max | Min | Max | | |
| VCC | Supply Voltage | 4.5 | 5.5 | 4.5 | 5.5 | 4.75 | 5.25 | V | |
| TA | Ambient Temperature | -55 | | -40 | 85 | 0 | 70 | °C | |
| TC | Case Temperature | | 125 | | | | | °C | |
| K | Delay Factor | -X Speed Grade | | 0.4 | 2.75 | 0.46 | 2.55 | | |
| | | -0 Speed Grade | | 0.39 | 1.82 | 0.4 | 1.67 | 0.46 | 1.55 |
| | | -1 Speed Grade | | 0.39 | 1.56 | 0.4 | 1.43 | 0.46 | 1.33 |
| | | -2 Speed Grade | | | | 0.4 | 1.35 | 0.46 | 1.25 |

DC CHARACTERISTICS over operating range

| Symbol | Parameter | Conditions | Min | Max | Unit |
|--------|----------------------------------|----------------------|---------|-----|------|
| VIH | Input HIGH Voltage | | 2.0 | | V |
| VIL | Input LOW Voltage | | | 0.8 | V |
| VOH | Output HIGH Voltage | IOH = -4 mA | 3.7 | | V |
| | | IOH = -8 mA | 2.4 | | V |
| | | IOH = -10 µA | VCC-0.1 | | V |
| VOL | Output LOW Voltage | IOL = 12 mA* | | 0.4 | V |
| | | IOL = 10 µA | | 0.1 | V |
| II | Input Leakage Current | VI = VCC or GND | -10 | 10 | µA |
| IOZ | 3-State Output Leakage Current | VI = VCC or GND | -10 | 10 | µA |
| CI | Input Capacitance [1] | | | 10 | pF |
| IOS | Output Short Circuit Current [2] | VO = GND | -10 | -80 | mA |
| | | VO = VCC | 30 | 140 | mA |
| ICC | D.C. Supply Current [3] | VI, VIO = VCC or GND | | 10 | mA |

*IOL = 12 mA for commercial range only. IOL = 8 mA for the industrial and military ranges.

Notes:

- [1] Capacitance is sample tested only. CI = 20 pF max on I/(SI).
- [2] Only one output at a time. Duration should not exceed 30 seconds.
- [3] Commercial temperature grade only. Maximum Icc for industrial grade is 15mA and for military grade is 20 mA. For AC conditions use the formula described in the Section 9 — Power vs Operating Frequency.
- [4] Stated timing for worst case Propagation Delay over process variation at VCC = 5.0V and TA = 25°C. Multiply by the appropriate Delay Factor, K, for speed grade, voltage and temperature settings as specified in the Operating Range.
- [5] These limits are derived from a representative selection of the slowest paths through the pASIC logic cell **including net delays**. Worst case delay values for specific paths should be determined from timing analysis of your particular design .



AC CHARACTERISTICS at VCC = 5V, TA = 25°C (K = 1.00)

Logic Cell

| Symbol | Parameter | Propagation Delays (ns) | | | | |
|--------|-------------------------|-------------------------|-----|-----|-----|-----|
| | | Fanout | | | | |
| | | 1 | 2 | 3 | 4 | 8 |
| tPD | Combinatorial Delay [5] | 1.7 | 2.2 | 2.6 | 3.2 | 5.3 |
| tSU | Setup Time [5] | 2.1 | 2.1 | 2.1 | 2.1 | 2.1 |
| tH | Hold Time | 0.0 | 0.0 | 0.0 | 0.0 | 0.0 |
| tCLK | Clock to Q Delay | 1.0 | 1.5 | 1.9 | 2.6 | 4.7 |
| tCWHI | Clock High Time | 2.0 | 2.0 | 2.0 | 2.0 | 2.0 |
| tCWLO | Clock Low Time | 2.0 | 2.0 | 2.0 | 2.0 | 2.0 |
| tSET | Set Delay | 1.7 | 2.2 | 2.6 | 3.2 | 5.3 |
| tRESET | Reset Delay | 1.5 | 1.9 | 2.2 | 2.7 | 4.4 |
| tSW | Set Width | 1.9 | 1.9 | 1.9 | 1.9 | 1.9 |
| tRW | Reset Width | 1.8 | 1.8 | 1.8 | 1.8 | 1.8 |

Input Cells

| Symbol | Parameter | Propagation Delays (ns) [4] | | | | | |
|--------|---------------------------------------|-----------------------------|-----|-----|-----|-----|-----|
| | | 1 | 2 | 3 | 4 | 6 | 8 |
| tIN | High Drive Input Delay [6] | 2.8 | 2.9 | 3.0 | 3.1 | 4.0 | 5.3 |
| tINI | High Drive Input, Inverting Delay [6] | 3.0 | 3.1 | 3.2 | 3.3 | 4.1 | 5.7 |
| tIO | Input Delay (bidirectional pad) | 1.4 | 1.9 | 2.2 | 2.9 | 4.7 | 6.5 |
| tGCK | Clock Buffer Delay [7] | 2.7 | 2.8 | 2.9 | 3.0 | 3.1 | 3.3 |
| tGCKHI | Clock Buffer Min High [7] | 2.0 | 2.0 | 2.0 | 2.0 | 2.0 | 2.0 |
| tGCKLO | Clock Buffer Min Low [7] | 2.0 | 2.0 | 2.0 | 2.0 | 2.0 | 2.0 |

Output Cell

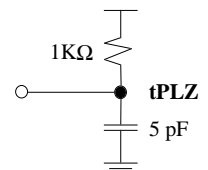
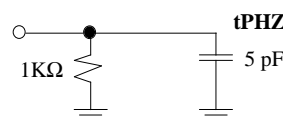
| Symbol | Parameter | Propagation Delays (ns) [4] | | | | |
|---------|------------------------------------|------------------------------|-----|-----|-----|-----|
| | | Output Load Capacitance (pF) | | | | |
| | | 30 | 50 | 75 | 100 | 150 |
| tOUTLH | Output Delay Low to High | 2.7 | 3.4 | 4.2 | 5.0 | 6.7 |
| tOUTHHL | Output Delay High to Low | 2.8 | 3.7 | 4.7 | 5.6 | 7.6 |
| tPZH | Output Delay Tri-state to High | 4.0 | 4.9 | 6.1 | 7.3 | 9.7 |
| tPZL | Output Delay Tri-state to Low | 3.6 | 4.2 | 5.0 | 5.8 | 7.3 |
| tPHZ | Output Delay High to Tri-state [8] | 2.9 | | | | |
| tPLZ | Output Delay Low to Tri-state [8] | 3.3 | | | | |

Notes:

[6] See High Drive Buffer Table for more information.

[7] Clock buffer fanout refers to the maximum number of flip flops per half column. The number of half columns used does not affect clock buffer delay.

[8] The following loads are used for tPXZ:





High Drive Buffer

| Symbol | Parameter | Clock Drivers Wired Together | Propagation Delays (ns) [4] | | | | |
|--------|--------------------------------------|---------------------------------|-----------------------------|-----|-----|-----|-----|
| | | | Fanout | | | | |
| | | | 12 | 24 | 48 | 72 | 96 |
| tIN | High Drive Input Delay | 1 | 5.3 | 6.7 | | | |
| | | 2 | | 4.5 | 6.6 | | |
| | | 3 | | | 5.3 | 6.2 | 7.2 |
| | | 4 | | | | 5.4 | 6.2 |
| tINI | High Drive Input, Inverting Delay | 1 | 5.7 | 7.2 | | | |
| | | 2 | | 4.6 | 6.8 | | |
| | | 3 | | | 5.5 | 6.4 | 7.4 |
| | | 4 | | | | 5.6 | 6.4 |

AC Performance

Propagation delays depend on routing, fanout, load capacitance, supply voltage, junction temperature, and process variation. The AC Characteristics are a design guide to provide initial timing estimates at nominal conditions. Worst case estimates are obtained when nominal propagation delays are multiplied by the appropriate Delay Factor, K, as specified in the Delay Factor table (Operating Range). The effects of voltage and temperature variation are illustrated in the graphs on page 4-47, K Factor versus Voltage and Temperature. The pASIC Development Tools incorporate data sheet AC Characteristics into the QDIF database for pre-place-and-route timing analysis. The SpDE Delay Modeler extracts specific timing parameters for precise path analysis or simulation results following place and route.

| | |
|--|--|
| <p>ORDERING INFORMATION</p> | <p><u>QL 16x24B - 1 PF144 C</u></p> |
| <p>QuickLogic pASIC device</p> | <p>Operating Range C = Commercial I = Industrial M = Military M/883C = MIL STD 883</p> |
| <p>pASIC device part number B = 0.65 micron CMOS</p> | <p>Package Code PL84 = 84-pin PLCC PF100 = 100-pin TQFP PF144 = 144-pin TQFP CG144 = 144-pin CPGA CF160 = 160-pin CQFP</p> |
| <p>Speed Grade X = quick 0 = fast 1 = faster 2 = fastest</p> | |